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焊接指导（2）

Guideline for Soldering (2)

3. 清洗：

Cleaning

ضي U ą ضي 30 Ð 3 № 50 Ð 30

ą ï ³ ╕ ╟ ῷ ą ╕ Ψ LED غ № H

w 300W ʅ ↕ ˜ LED H

ï r ' ῷ Ð ʅ Ψ LED H

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

*** 注意：** ʎ ↕ PCB غ ï r ï ʃ غج

ʒ PCB غ

*** Note:** This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..

使用注意事项（2）

Precautions (2)

3. 设计建议

Design C